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X-Ray Inspection System

The Dual-VU is a real-time x-ray inspection system with added vision image display. Unlike other x-ray inspection systems, this one provides simultaneous and congruent images of the device under inspection. The system provides both vision and x-ray inspection in a small footprint system. It has been particularly useful in ball grid array (BGA) applications having components on both sides, which can confuse the interpretation of the BGA x-ray image.

Glenbrook Technologies Inc., Randolph, NJ

Booth 2029

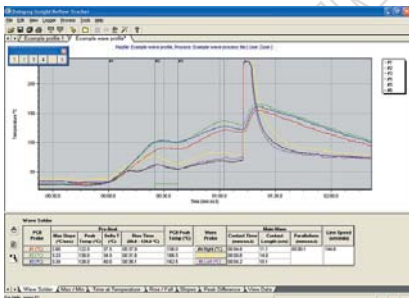


Miniature Magnetic Rotary Encoders

The new line of frictionless 9-bit (512 count) miniature magnetic encoders is available in industry-standard absolute, incremental or linear output formats. Speeds of over 30,000 rpm can be achieved with measurement accuracy better than 0.7°. Non-contact design provides reliable long-term operation by eliminating the need for seals or bearings. For harsh environments, compact sealed versions are also available with immunity to IP68. The mini mag encoders come in component, modular and packaged versions. Incremental output options include digital (128 ppr), analog, linear voltage and linear current modes.

Renishaw Inc., Hoffman Estates, IL

Booth 1300



Wave Solder Probe Kit

The low-cost wave solder probe kit can now adapt your Reflow Tracker Thermal Profiling System for monitoring the wave soldering process. Users can view all the critical wave process parameters in one easy-to-read table. The Insight software will then analyze data from both processes, ensuring compatibility of data throughout the factory and minimizing operator-training needs.

Datapaq Inc., Wilmington, MA

Booth 1471



Robotic Soldering Systems

The ECHO benchtop selective robotic solder system with Geyan solder feeder eliminates the possibility of solder balls or spattering. Fixturing capabilities securely hold even the most difficult parts, multiple wires or unusual configurations in place for accurate soldering. Point-to-point speed is up to 800 mm/sec. with repeatability of ± 0.01 mm (x, y and z axes) and $\pm 0.02^\circ$ (r axis). Work areas range from 8 x 8 in. to 20 x 20 in. Each system has a fully programmable iron tip cleaning cycle and a standard sponge cleaner or optional air blow cleaner.

Fancort Industries Inc., West Caldwell, NJ

Booth 1409

Placement Head

The Lightning placement head has a radial array of 30 modular, individually controlled spindles. The head has a duty cycle of 60 ms—a pick-to-pick or place-to-place performance that delivers chipshooting speeds in a platform system that maintains commonality of feeders, vision, heads and software with other platform equipment. Dual on-the-head optics allow the head to address a range of components, from 01005 to 30 x 30 mm, and supports component pre-orientation as well as on-the-head rejection for small parts. The plug-in spindle modules can be quickly and easily replaced and each contains a tiny Airkiss venturi vacuum generator to maintain a short and low maintenance vacuum path.

Universal Instruments Co., Binghamton, NY

Booth 355

Lead-Free Solder Paste

To help electronic assemblers meet the rapidly growing global initiatives requiring the removal of lead from their processes, ALPHA OM-338 lead-free solder paste provides soldering performance and a low cost of ownership. In addition, the solder paste has a wide reflow process.

Cookson Electronics, Foxborough, MA

Booth 1965

Tape Dispenser

The TDA080 electronic heavy-duty tape dispenser automatically dispenses and cuts virtually any tape, including duct tape. The dispenser is designed for continuous industrial use, accepts tape widths from 0.375 in. (9.5 mm) to 3.15 in. (80 mm) and cuts lengths from 3.15 in. (80 mm) to 394 in. (9999 mm). It comes with a standard 3 in. (76.2 mm) core, adjustable feed intervals and safety interlock and can be modified to dispense non-adhesive materials.

Start International, Addison, TX

Booth 1077

Lead-Free Solder Paste

NC-SMQ230 is an air reflow, no-clean solder paste specifically formulated to accommodate the high processing temperatures required by Sn/Ag/Cu and Sn/Ag lead-free alloy systems. The paste features extended stencil life and tack time.

Indium Corp. of America, Utica, NY

Booth 1351

Reworkable Underfill Encapsulant

CN-1453 is a new, silica-filled reworkable underfill encapsulant used to underfill flip chips, wafer level chip-scale packages (CSPs), CSPs and ball grid array (BGAs). Removal of defective components is accomplished by heating the component and the underfill encapsulant to 220°C. Underfill encapsulant residues are then easily scraped or brushed off. The encapsulant has a viscosity of 7500 cps at room temperature and is capable of flowing 18 mm, with a single-side dispense, in as little as 20 seconds. The encapsulant self-fillets, eliminating the need for seal passes to create complete and symmetrical fillets.

Zymet Inc., East Hanover, NJ
Booth 1363

X-Ray Inspection System

The TIGER (FXS-160.40) x-ray system now offers proprietary True X-Ray Intensity (TXI) control to assist operators in identifying production anomalies with consistent x-ray images. Unlike conventional techniques for maintaining image consistency that control the input level of high-voltage and x-ray tube current, TXI controls the output level of x-ray intensity during the image acquisition process, producing stable, permanent image quality. It also provides steady x-ray intensity after auto-start; long-term stability of x-ray intensity; and constant image contrast and brightness for recurring inspection tasks.

FEINFOCUS, Garbsen, Germany
Booth 1197

Manufacturing Software

The Navipoint Enterprise Performance Suite provides original equipment manufacturers (OEMs) with real-time visibility to operational information so that employees, customers and suppliers can be more responsive. It analyzes and presents enterprise, plant and departmental views of key performance indicators in a personalized portal. The software allows users to take actions through industry specific applications that streamline quoting, schedule sharing and order status tracking. It provides real-time information on product genealogy and supplier performance through a Web browser.

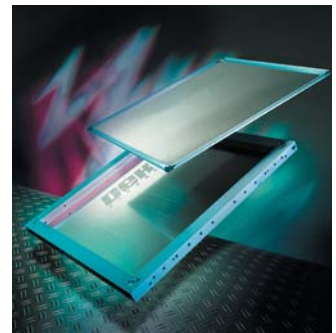
Cimnet Systems Inc., Downers Grove, IL
Booth 2041

Don't miss more products to be featured at APEX in our February APEX Product Spotlight!

Stencil System

VectorGuard is an advanced stencil technology that is easier to handle than conventional stencils. It is surrounded by a thin aluminum extrusion that makes it lighter, and, with the risks from sharp edges eliminated, it enhances operator safety. Its variable foils guarantee print performance and operator safety. The stencil's rigid construction protects the stencil body during handling and, because it does not use an aluminum frame like mesh mounted stencils, offers cost-savings and minimized storage capacity requirements.

DEK International GmbH, Flemington, NJ
Booth 1215



Split Vision Rework Station

The Marksman Intruder offers placement and reflow for all types of boards and components, including ball grid array (BGA) and lead-free applications. The station features a convection panel preheat system available in 900 W, 1600 W and 2400 W heater configurations that can duplicate original manufacturing temperature parameters. The system incorporates the P-300 controller with each profile containing up to 16 segments of ramp/soak combined with four integrated real-time thermocouples for profile development.

A.P.E., Key Largo, FL
Booth 1909



Tape Feeders

The fast-loading Agilis feeder is now available for 12 and 16 mm tapes. In addition to the new feeder sizes, MYDATA is introducing a new magazine with linear motion, which offer smooth, high speed and precision feeding, for 0201s or smaller components. In place of a traditional feeder wheel to pull the tape, the new drive features a solenoid tape-grabbing mechanism with auto adjust capability.

MYDATA Automation Inc., Rowley, MA
Booth 857



Lead-Free Solder Paste

Multicore LF320 is a lead-free solder paste optimized for reflow in air on a range of printed circuit board (PCB) assembly applications. Reflow profiles may also be extended with nitrogen. The paste requires a minimum peak reflow temperature of only 229°C. With a print speed range of 25 to 100 mm. (1.0 to 4.0 in.) and an abandon time of up to two hours, the paste offers excellent wetting on a range of surface finishes. The solder paste has been formulated to provide high resistance to slump and solder balling.

Henkel Loctite Corp., Industry, CA
Booth 1826

